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Global Die Bonder Equipment Market Data Survey Report 2025

https://marketpublishers.com/r/GB40F54FC2AEN.html
Date: September 2017
Pages: 75
Price: US$ 1,500.00 (Single User License)
ID: GB40F54FC2AEN

Abstracts

Summary

Die bonding is the process of attaching a die/chip to a substrate or package. Die bonding is accomplished by using one of the following processes: 1. Eutectic; 2. Solder; 3. Adhesive; 4. Glass or Silver-Glass

The global Die Bonder Equipment market will reach Volume Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

Besi

ASM Pacific Technology (ASMPT)

- Kulicke & Soffa
- Palomar Technologies
- Shinkawa
- DIAS Automation
- Toray Engineering
- Panasonic
- FASFORD TECHNOLOGY
- West-Bond
- Hybond

Major applications as follows:

- Integrated Device Manufacturers (IDMs)
- Outsourced Semiconductor Assembly and Test (OSAT)

Regional market size, production data and export & import:

- Asia-Pacific
- North America
- Europe
- South America
- Middle East & Africa

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